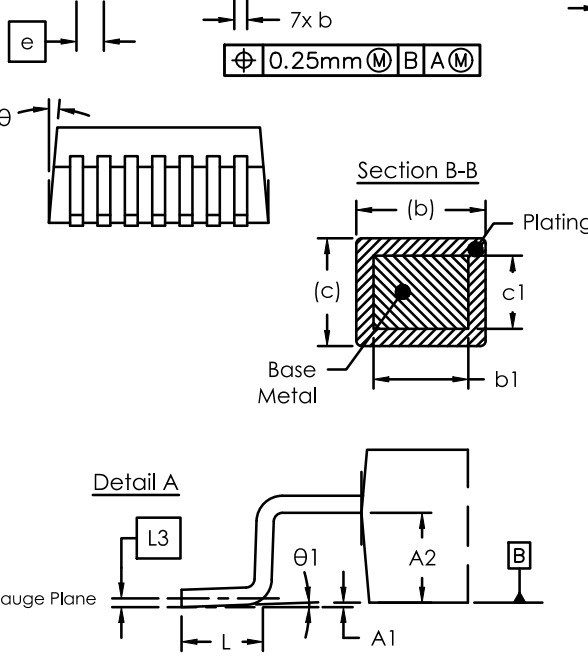
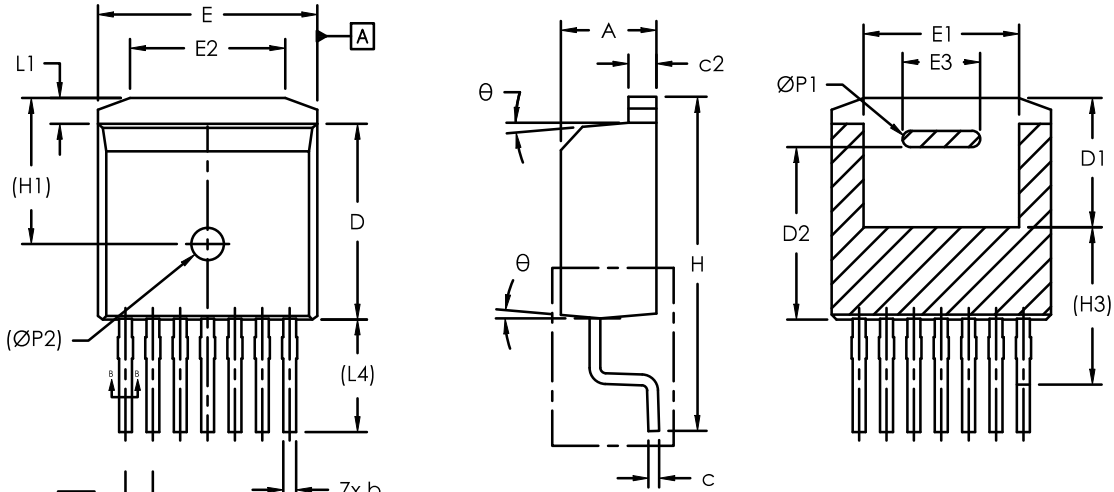


TO-263-7 10.18x9.08x4.43, 1.27P
CASE 418BA
ISSUE B

DATE 17 APR 2025



| SYM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | Min | Nom | Max |
| A | 4.30 | 4.43 | 4.56 |
| A1 | 0.00 | 0.13 | 0.25 |
| A2 | 2.45 | 2.60 | 2.75 |
| b | 0.50 | 0.60 | 0.70 |
| b1 | 0.50 | - | - |
| c | 0.40 | 0.50 | 0.60 |
| c1 | 0.40 | - | - |
| c2 | 1.20 | 1.30 | 1.40 |
| D | 8.93 | 9.08 | 9.23 |
| D1 | 5.85 | 6.00 | 6.15 |
| D2 | 7.90 | 8.00 | 8.10 |
| e | 1.27 BSC | | |
| E | 10.08 | 10.18 | 10.28 |
| E1 | 6.82 | 7.22 | 7.62 |
| E2 | 6.50 | 7.55 | 8.60 |
| E3 | 3.50 | 3.60 | 3.70 |
| H | 15.00 | 15.50 | 16.00 |
| H1 | 6.78 REF | | |
| H3 | 7.30 REF. | | |
| L | 1.90 | 2.20 | 2.50 |
| L1 | 0.98 | 1.20 | 1.42 |
| L3 | 0.25 BSC | | |
| L4 | 5.22 REF | | |
| ØP1 | 0.65 | 0.75 | 0.85 |
| ØP2 | 1.50 REF | | |
| θ | 5° | | |
| θ1 | 3° | | |

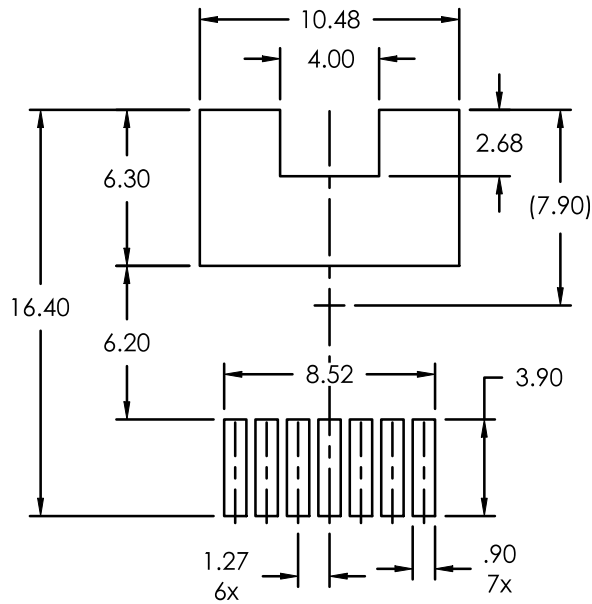
Notes:

1. Dimensioning and Tolerancing as per ASME Y14.5M, 2018.
2. Controlling Dimension : Millimeters
3. Package body sides exclude mold flash and gate burrs.
4. Dimension L is measured on gauge plane.
5. Dimension c1 and b1 applies to base metal only.

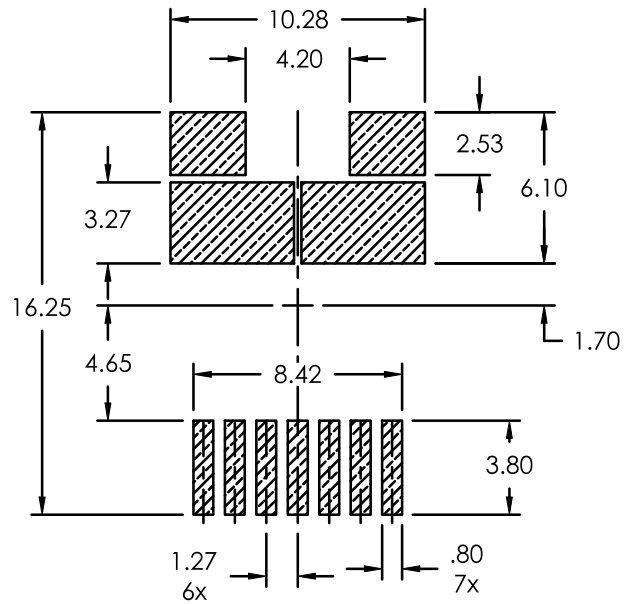
| | | |
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RECOMMENDED PCB FOOTPRINT

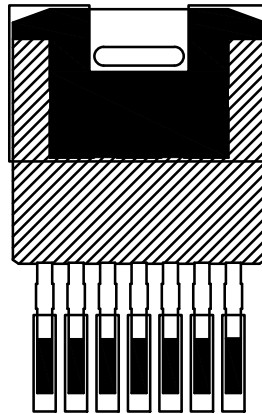


RECOMMENDED STENCIL APERTURE



NOTE: LAND PATTERN AND STENCIL APERTURE DIMENSIONS SERVE ONLY AS AN INITIAL GUIDE. END-USER PCB DESIGN RULES AND TOLERANCES SHOULD ALWAYS PREVAIL.

PCB FOOTPRINT with PACKAGE OVERLAY



- AREA IN CONTACT WITH THE PACKAGE
- MOLD COMPOUND

| | | |
|-------------------------|--|--|
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